

1.TYPE RD3G500GN

2.STRUCTURE SILICON N-CHANNEL MOS FET

3.APPLICATIONS SWITCHING

 4.ABSOLUTE MAXIMUM RATINGS [$T_a=25^{\circ}\text{C}$]

DRAIN-SOURCE VOLTAGE		V_{DSS}	...	40V	
GATE-SOURCE VOLTAGE		V_{GSS}	...	$\pm 20\text{V}$	
DRAIN CURRENT	CONTINUOUS	I_D	...	$\pm 50\text{A}$	
	PULSED	I_{DP}	...	$\pm 100\text{A}$	$P_w \leq 10 \mu\text{s}$, Duty cycle $\leq 1\%$
SOURCE CURRENT	CONTINUOUS	I_S	...	29A	
(BODY DIODE)	PULSED	I_{SP}	...	100A	$P_w \leq 10 \mu\text{s}$, Duty cycle $\leq 1\%$
AVALANCHE CURRENT		I_{AS}	...	50A	$L \approx 50\mu\text{H}$, $V_{DD}=20\text{V}$, $R_G=25 \Omega$ STARTING $T_{ch}=25^{\circ}\text{C}$ See Fig.3-1, 3-2
AVALANCHE ENERGY		E_{AS}	...	94mJ	$L \approx 50\mu\text{H}$, $V_{DD}=20\text{V}$, $R_G=25 \Omega$ STARTING $T_{ch}=25^{\circ}\text{C}$ See Fig.3-1, 3-2
POWER DISSIPATION		P_D	...	35W	$T_c=25^{\circ}\text{C}$
CHANNEL TEMPERATURE		T_{ch}	...	150°C	
RANGE OF STORAGE TEMPERATURE		T_{stg}	...	$-55 \sim 150^{\circ}\text{C}$	
5.THERMAL RESISTANCE					
CHANNEL TO CASE		$R_{th(ch-c)}$	...	3.5°C/W	$T_c=25^{\circ}\text{C}$

*Limited only by maximum channel temperature allowed.

DESIGN	CHECK	APPROVAL	DATE: 10/DEC/2014	SPECIFICATION No. TSQ03139-RD3G500GN
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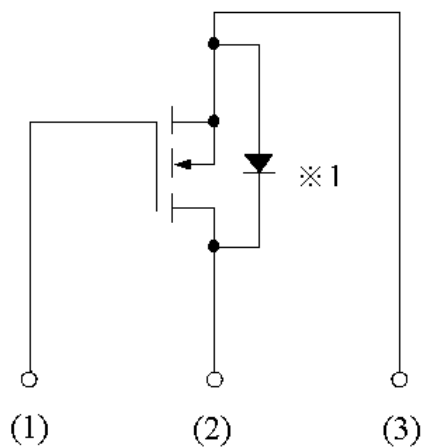
6.ELECTRICAL CHARACTERISTICS [$T_a=25^{\circ}\text{C}$]

PARAMETER	ITEM	CONDITION		MIN.	TYP.	MAX.
GATE-SOURCE-LEAKAGE	I _{GSS}	V _{GS} =±20V / V _{DS} =0V		–	–	±500nA
DRAIN-SOURCE BREAKDOWN VOLTAGE	V _{(BR)DSS}	I _D =1mA / V _{GS} =0V		40V	–	–
ZERO GATE VOLTAGE DRAIN CURRENT	I _{DSS}	V _{DS} =40V / V _{GS} =0V		–	–	1uA
GATE THRESHOLD VOLTAGE	V _{GS(th)}	V _{GS} =V _{DS} / I _D =1mA		1.0V	–	2.5V
STATIC DRAIN-SOURCE ON-STATE RESISTANCE	R _{DS(on)} *PULSED	I _D =50A / V _{GS} =10V		–	3.9mΩ	4.9mΩ
		I _D =50A / V _{GS} =4.5V		–	4.7mΩ	6.3mΩ
FORWARD TRANSFER ADMITTANCE	Y _{fs} *PULSED	V _{DS} =5V / I _D =25A		25S	–	–
INPUT CAPACITANCE	C _{iss}	V _{DS} =20V V _{GS} =0V f=1MHz		–	2280pF	–
OUTPUT CAPACITANCE	C _{oss}			–	370pF	–
REVERSE TRANSFER CAPACITANCE	C _{rss}			–	100pF	–
TURN-ON DELAY TIME	t _{d(on)} *PULSED	V _{DD} ≈20V I _D =50A V _{GS} =10V R _L =0.4Ω R _G =10Ω See Fig.1-1, 1-2		–	12.5ns	–
RISE TIME	t _r *PULSED			–	7.5ns	–
TURN-OFF DELAY TIME	t _{d(off)} *PULSED			–	65ns	–
FALL TIME	t _f *PULSED			–	10ns	–
TOTAL GATE CHARGE	Q _g *PULSED	V _{DD} ≈20V I _D =50A See Fig.2-1, 2-2	V _{GS} =10V	–	31nC	–
				–	16nC	–
GATE-SOURCE CHARGE	Q _{gs} *PULSED		V _{GS} =4.5V	–	5.9nC	–
GATE-DRAIN CHARGE	Q _{gd} *PULSED			–	4.5nC	–

BODY DIODE (SOURCE-DRAIN)

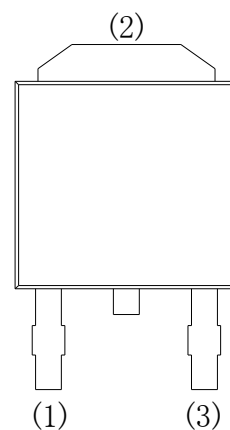
PARAMETER	ITEM	CONDITION	MIN.	TYP.	MAX.
FORWARD VOLTAGE	V_{SD} *PULSED	$I_S=29\text{A} / V_{GS}=0V$	–	–	1.2V

7.INNER CIRCUIT

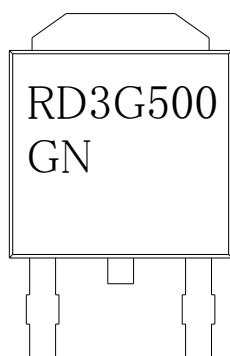


※1 BODY DIODE

- (1) GATE
- (2) DRAIN
- (3) SOURCE



8.MARKING



9. MEASUREMENT CIRCUIT

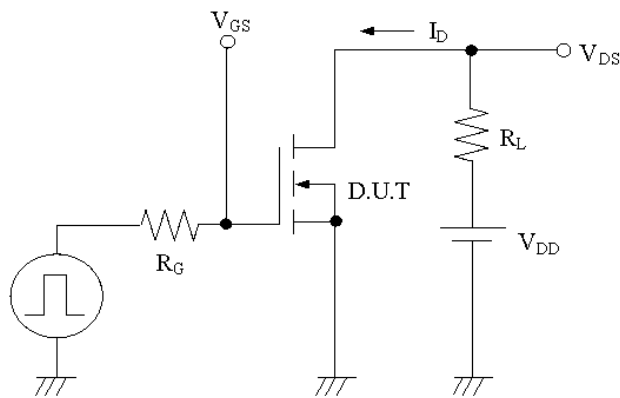


Fig.1-1 SWITCHING TIME MEASUREMENT CIRCUIT

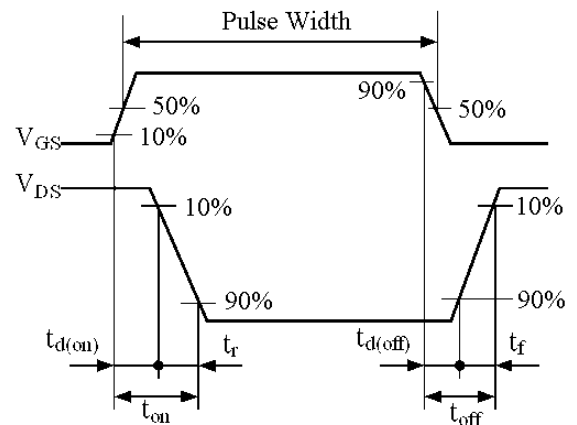


Fig.1-2 SWITCHING WAVEFORMS

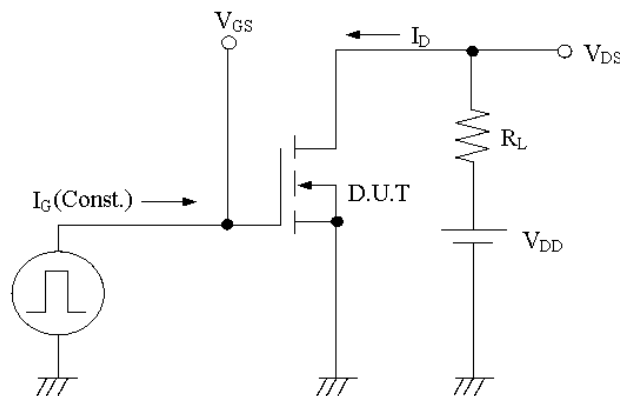


Fig.2-1 GATE CHARGE MEASUREMENT CIRCUIT

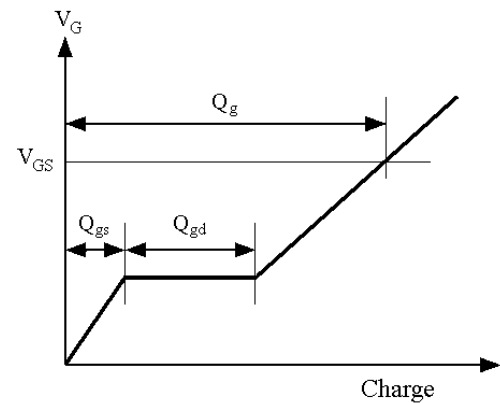


Fig.2-2 GATE CHARGE WAVEFORM

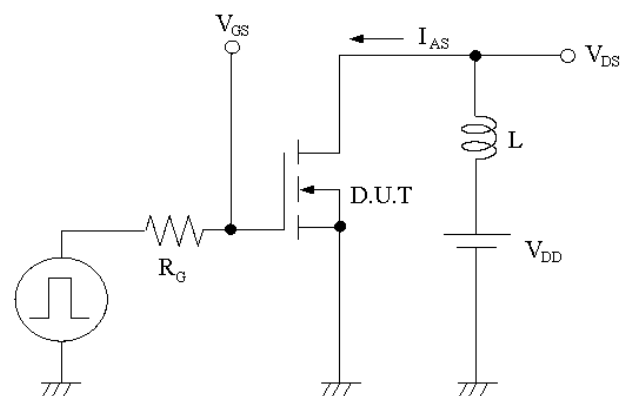


Fig.3-1 AVALANCHE MEASUREMENT CIRCUIT

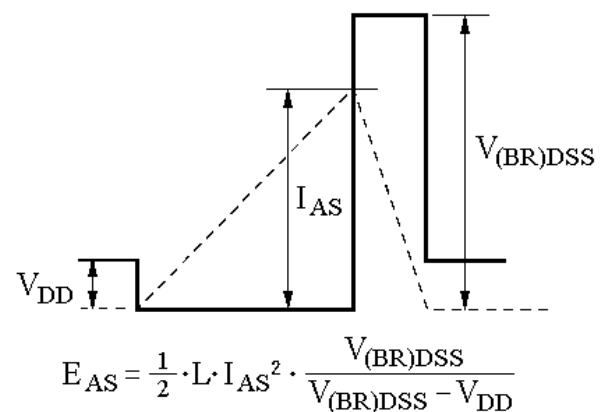


Fig.3-2 AVALANCHE WAVEFORM